

1525
AUG 16 2004

TRANSMITTAL LETTER
(General - Patent Pending)

Docket No.
P0338DIV

In Re Application Of: Chun-Cheng Tsao and John Valliant

Application No.	Filing Date	Examiner	Customer No.	Group Art Unit	Confirmation No.
10/693,310	10/24/2003	Shantese McDonald		3723	

Title: Method and Apparatus for Global Die Thinning and Polishing of Flip-Chip Packaged Integrated Circuits

COMMISSIONER FOR PATENTS:

Transmitted herewith is:

Certificate of Mailing by First-Class Mail
Amendment Transmittal Letter
Amendment and Response to Office Action (14 pp)
Credit Card Payment Form
Return Receipt Postcard

in the above identified application.

- ☐ No additional fee is required.
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- ☐ Charge the amount of _____
- ☐ Credit any overpayment.
- ☐ Charge any additional fee required.
- ☒ Payment by credit card. Form PTO-2038 is attached.

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Dated: August 11, 2004

Signature

Deborah W. Wenocur, Reg. No. 40,221
Agent for Applicant
c/o Shelly Garrett
Credence Systems Corp.
1421 California Circle
Milpitas, CA 95035

I hereby certify that this correspondence is being deposited with the United States Postal Service with sufficient postage as first class mail in an envelope addressed to the "Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450" [37 CFR 1.8(a)] o.

(Date) Aug. 13, 2004


Signature of Person Mailing Correspondence

Deborah W. Wenocur

Typed or Printed Name of Person Mailing Correspondence

CC:

CERTIFICATE OF MAILING BY FIRST CLASS MAIL (37 CFR 1.8)

Applicant(s): Chun-Cheng Tsao and John Valliant

Docket No.

P0338DIV

Application No.

10/693,310

Filing Date

10/24/2003

Examiner

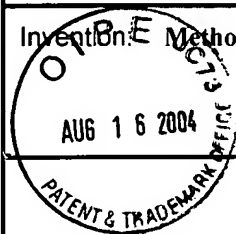
Shantese McDonald

Customer No.

Group Art Unit

3723

Invention: Method and Apparatus for Global Die Thinning and Polishing of Flip-Chip Packaged Integrated Circuit

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is being deposited with the United States Postal Service with sufficient postage as first class mail in an envelope addressed to "Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450" [37 CFR 1.8(a)] on
August 12, 2004

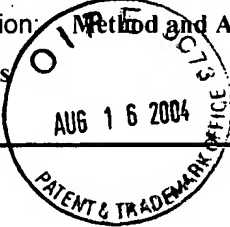
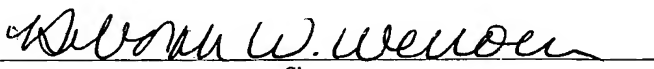
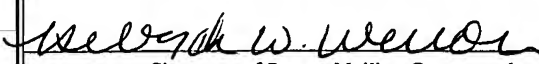
(Date)

Deborah W. Wenocur

(Typed or Printed Name of Person Mailing Correspondence)

(Signature of Person Mailing Correspondence)

Note: Each paper must have its own certificate of mailing.

AMENDMENT TRANSMITTAL LETTER (Large Entity)				Docket No. P0338DIV	
Applicant(s): Chun-Cheng Tsao and John Valliant					
Application No. 10/693,310	Filing Date 10/24/2003	Examiner Shantese McDonald	Customer No.	Group Art Unit 3723	Confirmation No.
Invention: Method and Apparatus for Global Die Thinning and Polishing of Flip-Chip Packaged Integrated Circuits					
					
COMMISSIONER FOR PATENTS:					
Transmitted herewith is an amendment in the above-identified application.					
The fee has been calculated and is transmitted as shown below.					
CLAIMS AS AMENDED					
	CLAIMS REMAINING AFTER AMENDMENT	HIGHEST # PREV. PAID FOR	NUMBER EXTRA CLAIMS PRESENT	RATE	ADDITIONAL FEE
TOTAL CLAIMS	29 -	29 =	0 x	\$18.00	\$0.00
INDEP. CLAIMS	8 -	5 =	3 x	\$86.00	\$258.00
Multiple Dependent Claims (check if applicable) <input type="checkbox"/>					\$0.00
TOTAL ADDITIONAL FEE FOR THIS AMENDMENT					\$258.00
<input type="checkbox"/> No additional fee is required for amendment. <input type="checkbox"/> Please charge Deposit Account No. _____ in the amount of _____ <input type="checkbox"/> A check in the amount of _____ to cover the filing fee is enclosed. <input type="checkbox"/> The Director is hereby authorized to charge payment of the following fees associated with this communication or credit any overpayment to Deposit Account <input type="checkbox"/> Any additional filing fees required under 37 C.F.R. 1.16. <input type="checkbox"/> Any patent application processing fees under 37 CFR 1.17. <input checked="" type="checkbox"/> Payment by credit card. Form PTO-2038.					
WARNING: Information on this form may become public. Credit card information should not be included on this form. Provide credit card information and authorization on PTO-2038.					
 Signature			Dated: August 11, 2004		
Deborah W. Wenocur, Reg. No. 40,221 Agent for Applicant c/o Shelly Garrett Credence Systems Corp. 1421 California Circle Milpitas, CA. 95035			I hereby certify that this correspondence is being deposited with the United States Postal Service with sufficient postage as first class mail in an envelope addressed to "Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450" [37 CFR 1.8(a)] on <u>August 12, 2004</u> (Date)  Signature of Person Mailing Correspondence Deborah W. Wenocur Typed or Printed Name of Person Mailing Correspondence		
CC:					



P0338DIV

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of:

Applicant: Chung-Chen Tsao and John Valliant) Grp Art Unit: 3723
)
Assignee: Credence Systems Corporation) Ex: Shantese McDonald
)
Serial Number: 10/693,310)
)
Filed: October 24, 2003)
)
For: METHOD AND APPARATUS FOR)
BACKSIDE DIE THINNING AND)
POLISHING OF PACKAGED)
INTEGRATED CIRCUITS)
)

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Dear Sir,

AMENDMENT AND RESPONSE TO OFFICE ACTION

This is in response to the Office Action dated May 31, 2004.

Please amend the instant application as follows:

08/17/2004 JADD01 00000015 10693310

01 FC:1201

258.00 OP